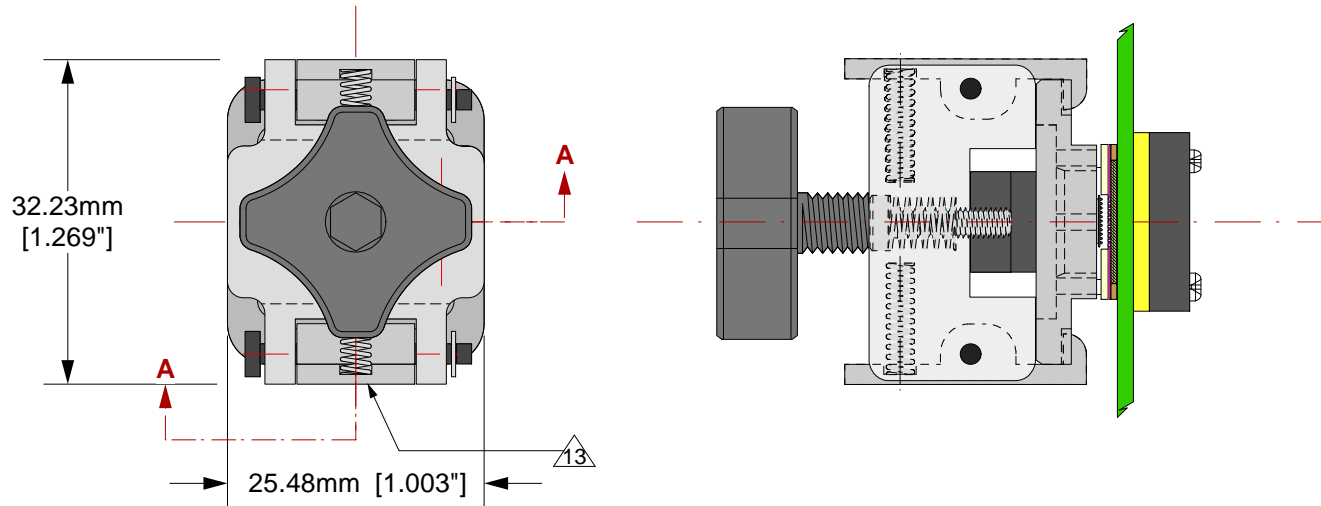
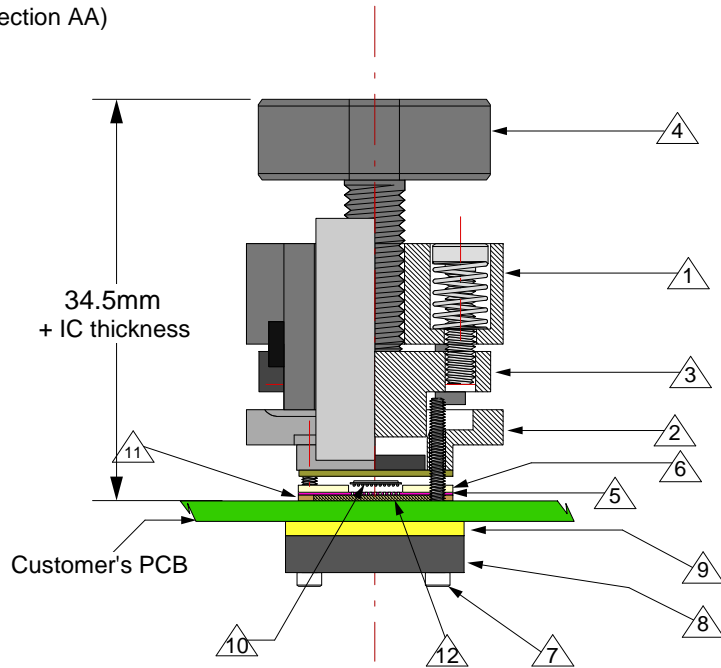


Top View



Side View
(Section AA)




Features

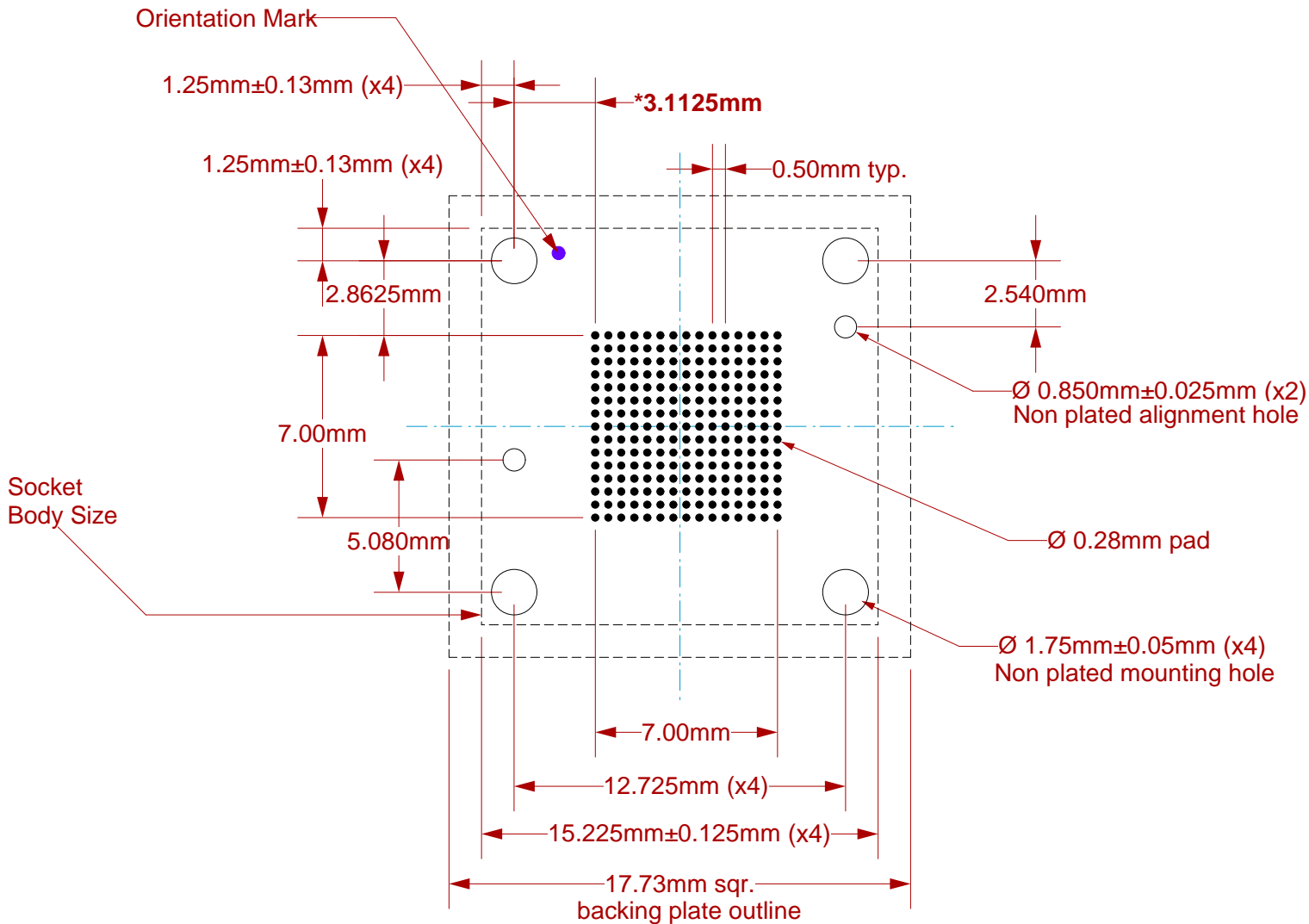
- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Materials:

- 1 Clam Shell Lid: Black anodized Aluminum. Height = 16.5 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 8.5 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 25 mm, Fluted Knob
- 5 Ball Guide: Kapton polyimide.
- 6 IC Guide: Torlon
- 7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- 8 Backing Plate: Black anodized Aluminum. Thickness= 4mm
- 9 Insulation Plate: FR4/G10
- 10 Customer's BGA IC
- 11 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- 12 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 13 Latch: Black anodized Aluminum.

All Tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

	CG-BGA-5002 Drawing	Status: Released	Scale: -	Rev: B
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 9/13/07	
		File: CG-BGA-5002 Dwg.mcd	Modified: 09/17/14 , DH	




Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

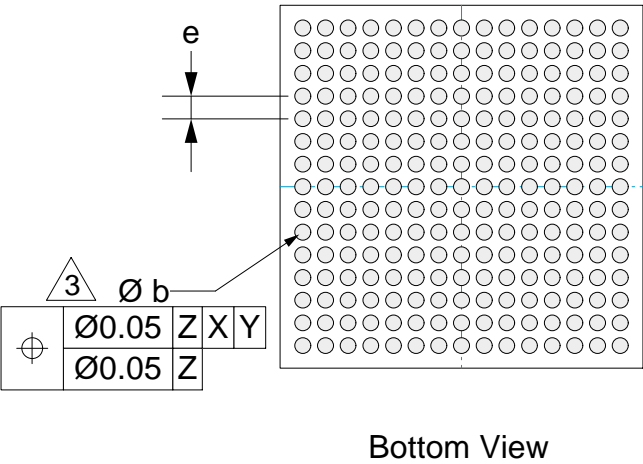
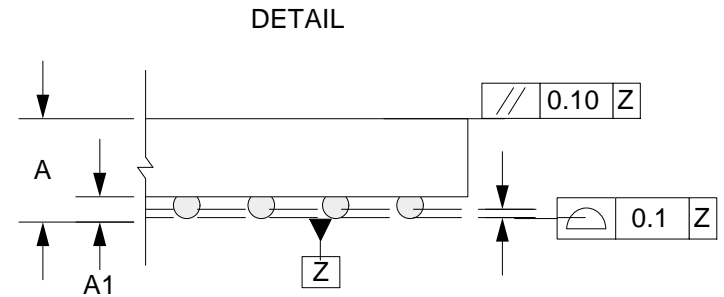
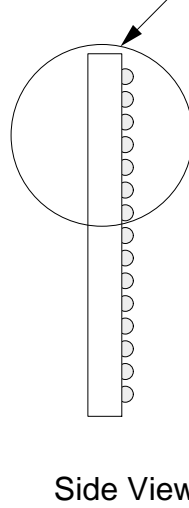
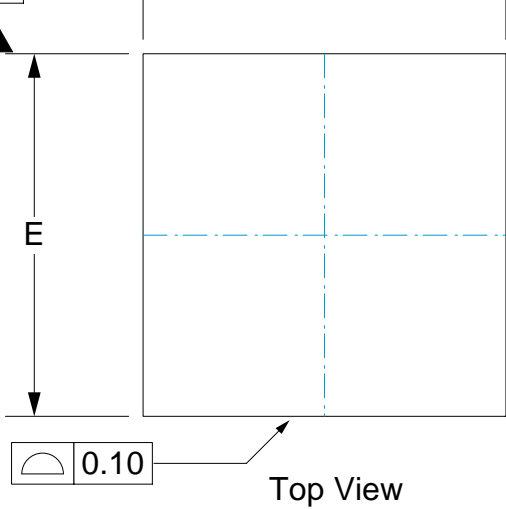
All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

Recommended PCB Layout Tolerances:
 $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.
All dimensions are in mm.

CG-BGA-5002 Drawing		Status: Released	Scale: 4:1	Rev: B
 <p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: J. Glab		Date: 9/13/07	
	File: CG-BGA-5002 Dwg.mcd		Modified: 09/17/14, DH	






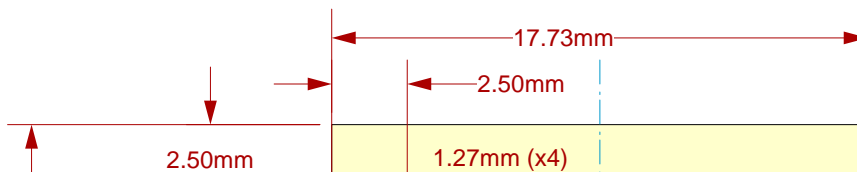
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A	0.74	1.0
A1	0.18	0.28
b	0.29	0.35
D	8.0 BSC	
E	8.0 BSC	
e	0.5 BSC	

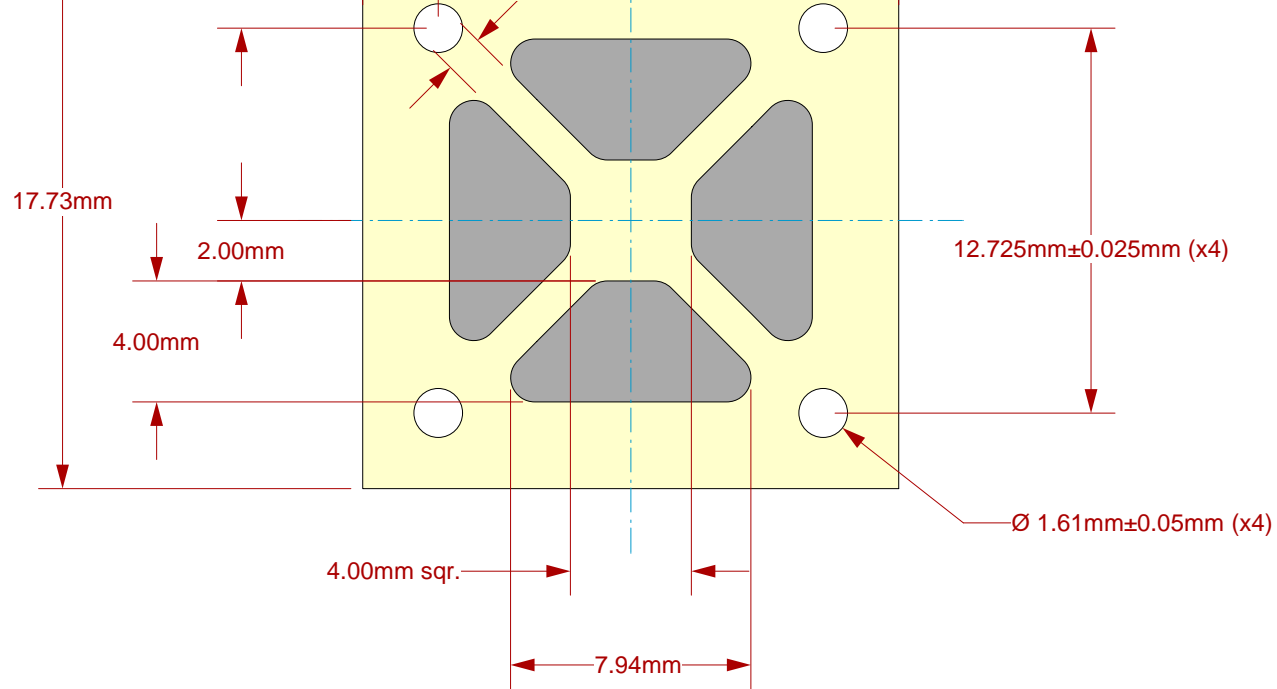
15 x 15 array

 <p>CG-BGA-5002 Drawing © 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Status: Released	Scale: -	Rev: B
	Drawing: J. Glab		Date: 9/13/07
	File: CG-BGA-5002 Dwg.mcd		Modified: 09/17/14, DH

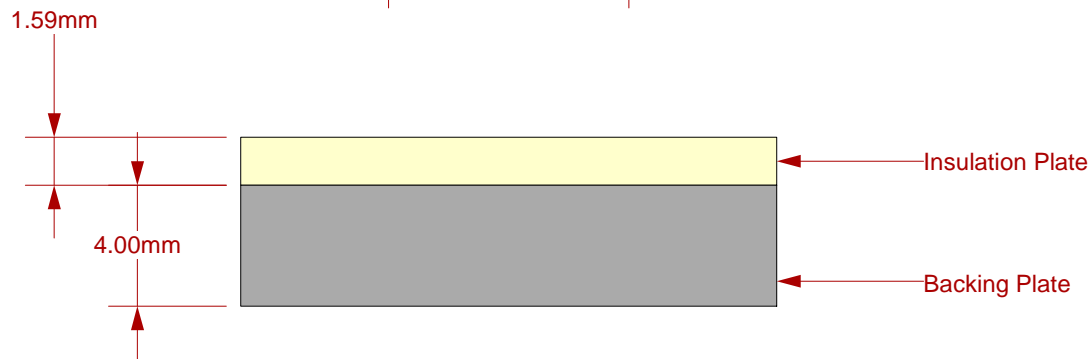
PAGE 3 of 4



Top View




Side View



USE DXF DATA

Description: Backing Plate with Insulation Plate

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)

	CG-BGA-5002 Drawing	Status: Released	Scale: -	Rev: B
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		File: CG-BGA-5002 Dwg.mcd		Modified: 09/17/14, DH